

# VS-25TTS...PbF Series, VS-25TTS...-M3 Series

## Vishay Semiconductors

ABSOLUTE MAXIMUM RATINGS								
PARAMETER	SYMBOL	TEST SOMBITIONS		VALUES		UNITS		
PARAMETER	SYMBOL TEST CONDITIONS		TYP.	MAX.				
Maximum average on-state current	I <sub>T(AV)</sub>	T <sub>C</sub> = 93 °C, 180° conduc	T <sub>C</sub> = 93 °C, 180° conduction half sine wave					
Maximum RMS on-state current	I <sub>RMS</sub>			25		Α		
Maximum peak, one-cycle,	L	10 ms sine pulse, rated \	V <sub>RRM</sub> applied	2	70	_ ^		
non-repetitive surge current	I <sub>TSM</sub>	10 ms sine pulse, no volt	tage reapplied	320				
Maximum I <sup>2</sup> t for fusing	I <sup>2</sup> t	10 ms sine pulse, rated V <sub>RRM</sub> applied			365			
Maximum i-t for fusing	I-ι	10 ms sine pulse, no voltage reapplied		515		- A <sup>2</sup> s		
Maximum $I^2\sqrt{t}$ for fusing	I²√t	t = 0.1 to 10 ms, no voltage reapplied			52	A²√s		
Maximum on-state voltage drop	$V_{TM}$	16 A, T <sub>J</sub> = 25 °C		1.	25	V		
On-state slope resistance	r <sub>t</sub>	T 105 °C		12.0		mΩ		
Threshold voltage	V <sub>T(TO)</sub>	- T <sub>J</sub> = 125 °C		1.0		V		
Maximum reverse and direct leakage current	1/1	T <sub>J</sub> = 25 °C	V Potod V/	0.5				
Maximum reverse and direct leakage current	$I_{RM}/I_{DM}$	$V_R = Rated V_{RRM}/V_{DRM}$		1	0			
Holding current	l <sub>Η</sub>	Anode supply = 6 V, resistive load, initial $I_T$ = 1 A, $T_J$ = 25 $^{\circ}C$		-	150	mA		
Maximum latching current	lι	Anode supply = 6 V, resistive load, $T_J = 25$ °C		200				
Maximum rate of rise of off-state voltage	dV/dt	$T_J = T_J \text{ max., linear to } 80 ^{\circ}\text{C}, V_{DRM} = R_g - k = Open$			500			
Maximum rate of rise of turned-on current	dl/dt			150		A/µs		

TRIGGERING					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Maximum peak gate power	$P_{GM}$		8.0	w	
Maximum average gate power	$P_{G(AV)}$		2.0		
Maximum peak positive gate current	+ I <sub>GM</sub>		1.5	Α	
Maximum peak negative gate voltage	- V <sub>GM</sub>		10	V	
	I <sub>GT</sub>	Anode supply = 6 V, resistive load, T <sub>J</sub> = - 10 °C	60	mA	
Maximum required DC gate current to trigger		Anode supply = 6 V, resistive load, T <sub>J</sub> = 25 °C	45		
		Anode supply = 6 V, resistive load, T <sub>J</sub> = 125 °C	20		
	V <sub>GT</sub>	Anode supply = 6 V, resistive load, T <sub>J</sub> = - 10 °C	2.5		
Maximum required DC gate voltage to trigger		Anode supply = 6 V, resistive load, T <sub>J</sub> = 25 °C	2.0	v	
voltage to trigger		Anode supply = 6 V, resistive load, T <sub>J</sub> = 125 °C	1.0	V	
Maximum DC gate voltage not to trigger	$V_{GD}$	T. = 125 °C V Potod volue	0.25		
Maximum DC gate current not to trigger	$I_{GD}$	T <sub>J</sub> = 125 °C, V <sub>DRM</sub> = Rated value	2.0	mA	

SWITCHING						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Typical turn-on time	t <sub>gt</sub>	T <sub>J</sub> = 25 °C	0.9			
Typical reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 125 °C	4	μs		
Typical turn-off time	t <sub>q</sub>	1] = 120 0	110			



www.vishay.com

### Vishay Semiconductors

THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER		SYMBOL	SYMBOL TEST CONDITIONS		UNITS	
Maximum junction and storage temperature range		T <sub>J</sub> , T <sub>Stg</sub>		-40 to 125	°C	
Maximum thermal resistance, junction to case		$R_{thJC}$	DC operation	1.1		
Maximum thermal resistance, junction to ambient		R <sub>thJA</sub>		62	°C/W	
Typical thermal resistance, case to heatsink		R <sub>thCS</sub>	Mounting surface, smooth and greased	0.5		
Approximate weight				2	g	
Approximate weight				0.07	OZ.	
Mounting torque —	minimum			6 (5)	kgf · cm	
	maximum			12 (10)	(lbf · in)	
Maddanadada			Case style TO-220AB		TS08	
Marking device					ΓS12	

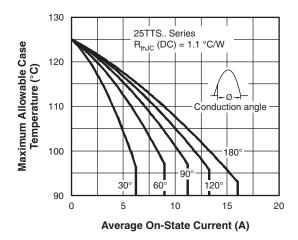


Fig. 1 - Current Rating Characteristics

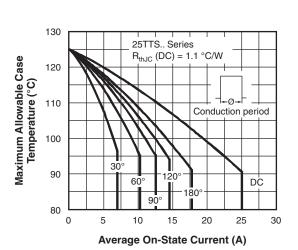


Fig. 2 - Current Rating Characteristics

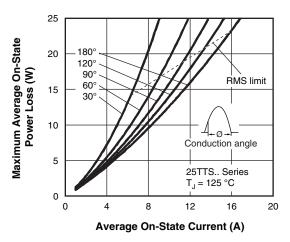


Fig. 3 - On-State Power Loss Characteristics

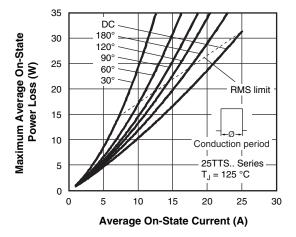


Fig. 4 - On-State Power Loss Characteristics



www.vishay.com

### Vishay Semiconductors

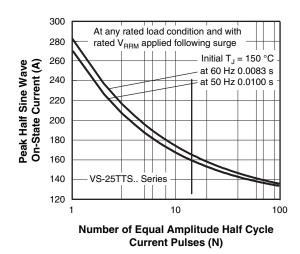


Fig. 5 - Maximum Non-Repetitive Surge Current

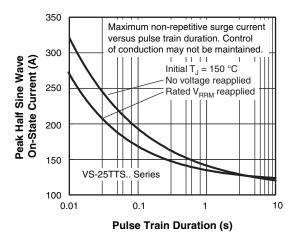


Fig. 6 - Maximum Non-Repetitive Surge Current

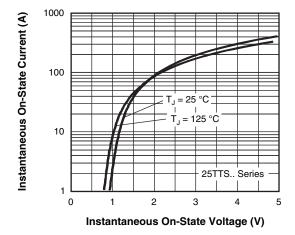


Fig. 7 - On-State Voltage Drop Characteristics

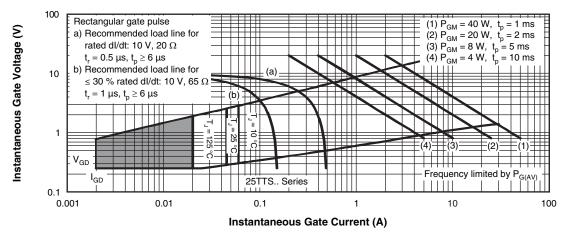


Fig. 8 - Gate Characteristics

## VS-25TTS...PbF Series, VS-25TTS...-M3 Series

### Vishay Semiconductors

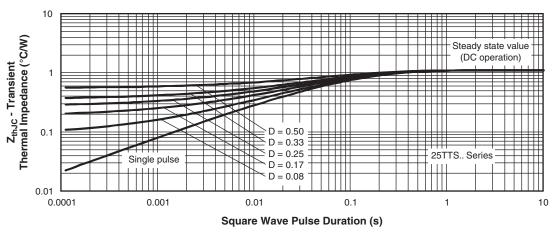
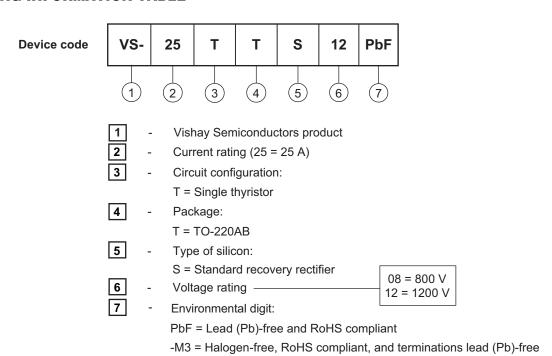


Fig. 9 - Thermal Impedance ZthJC Characteristics

#### **ORDERING INFORMATION TABLE**



ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-25TTS08PbF	50	1000	Antistatic plastic tubes			
VS-25TTS08-M3	50	1000	Antistatic plastic tubes			
VS-25TTS12PbF	50	1000	Antistatic plastic tubes			
VS-25TTS12-M3	50	1000	Antistatic plastic tubes			

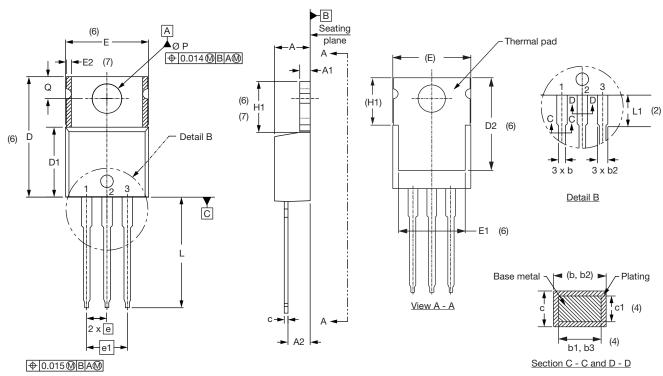
LINKS TO RELATED DOCUMENTS				
Dimensions <u>www.vishay.com/doc?95222</u>				
Dout moulting information	TO-220AB PbF	www.vishay.com/doc?95225		
Part marking information	TO-220AB -M3	www.vishay.com/doc?95028		



### Vishay Semiconductors

### **TO-220AB**

#### **DIMENSIONS** in millimeters and inches



#### Lead assignments

#### <u>Diodes</u>

- 1. Anode/open
- 2. Cathode
- 3. Anode

#### Conforms to JEDEC outline TO-220AB

SYMBOL	MILLIN	IETERS	INC	NOTES	
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.56	2.92	0.101	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
С	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.25	0.585	0.600	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	12.88	0.460	0.507	6

SYMBOL	MILLIM	IETERS	INC	NOTES	
STIMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
E	10.11	10.51	0.398	0.414	3, 6
E1	6.86	8.89	0.270	0.350	6
E2	-	0.76	-	0.030	7
е	2.41	2.67	0.095	0.105	
e1	4.88	5.28	0.192	0.208	
H1	6.09	6.48	0.240	0.255	6, 7
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
ØΡ	3.54	3.73	0.139	0.147	
Q	2.60	3.00	0.102	0.118	
θ	90° to 93°		90° to 93°		

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimensions E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC TO-220, except A2 (maximum) and D2 (minimum) where dimensions are derived from the actual package outline

Lead tip

### **Legal Disclaimer Notice**



Vishay

#### **Disclaimer**

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.